

Title (en)
SiC-BOUND DIAMOND HARD MATERIAL PARTICLES, POROUS COMPONENT FORMED WITH SiC-BOUND DIAMOND PARTICLES, METHOD OF PRODUCING SAME AND USE THEREOF

Title (de)
SiC-GEBUNDENE DIAMANTHARTSTOFFPARTIKEL, PORÖSES BAUTEIL, DAS MIT SiC-GEBUNDENEN DIAMANTPARTIKELN GEBILDET IST, VERFAHREN ZU DEREN HERSTELLUNG SOWIE DEREN VERWENDUNG

Title (fr)
PARTICULE DE CÉRAMIQUE DE DIAMANT RELIÉE À DU SiC, MODULE POREUX QUI EST CONSTITUÉ DE PARTICULES DE DIAMANT RELIÉES À DU SiC, LEUR PROCÉDÉ DE FABRICATION ET LEUR UTILISATION

Publication
EP 3765428 A1 20210120 (DE)

Application
EP 19713380 A 20190314

Priority
• DE 102018203882 A 20180314
• EP 2019056457 W 20190314

Abstract (en)
[origin: WO2019175333A1] The invention relates to SiC-bound diamond hard material particles, a porous component formed with SiC-bound diamond particles, methods for producing same and the use thereof. Diamond hard material particles and components have a composition of 30 vol. % to 65 vol. % diamond, 70 vol. % to 35 vol. % SiC and 0 to 30 vol. % Si, and a component has a porosity in the range of 10% to 40%.

IPC 8 full level
C04B 35/52 (2006.01); **C04B 35/528** (2006.01); **C04B 35/565** (2006.01); **C09K 3/14** (2006.01)

CPC (source: EP KR US)
C04B 35/52 (2013.01 - EP KR US); **C04B 35/528** (2013.01 - EP KR); **C04B 35/565** (2013.01 - EP KR); **C04B 35/573** (2013.01 - US); **C04B 35/62695** (2013.01 - US); **C04B 35/62839** (2013.01 - US); **C04B 35/65** (2013.01 - US); **C04B 38/067** (2013.01 - US); **C09K 3/1436** (2013.01 - US); **C09K 3/1445** (2013.01 - EP KR); **C04B 2235/3826** (2013.01 - EP KR US); **C04B 2235/427** (2013.01 - EP KR US); **C04B 2235/428** (2013.01 - US); **C04B 2235/5427** (2013.01 - EP KR); **C04B 2235/5436** (2013.01 - EP KR US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2019175333 A1 20190919; BR 112020018495 A2 20201229; CN 112119051 A 20201222; DE 102018203882 A1 20190919; EP 3765428 A1 20210120; JP 2021517546 A 20210726; JP 7335885 B2 20230830; KR 20200143390 A 20201223; RU 2020132167 A 20220414; US 12024666 B2 20240702; US 2021002534 A1 20210107

DOCDB simple family (application)
EP 2019056457 W 20190314; BR 112020018495 A 20190314; CN 201980027257 A 20190314; DE 102018203882 A 20180314; EP 19713380 A 20190314; JP 2020548677 A 20190314; KR 20207029346 A 20190314; RU 2020132167 A 20190314; US 201916980570 A 20190314